

FIG.1A

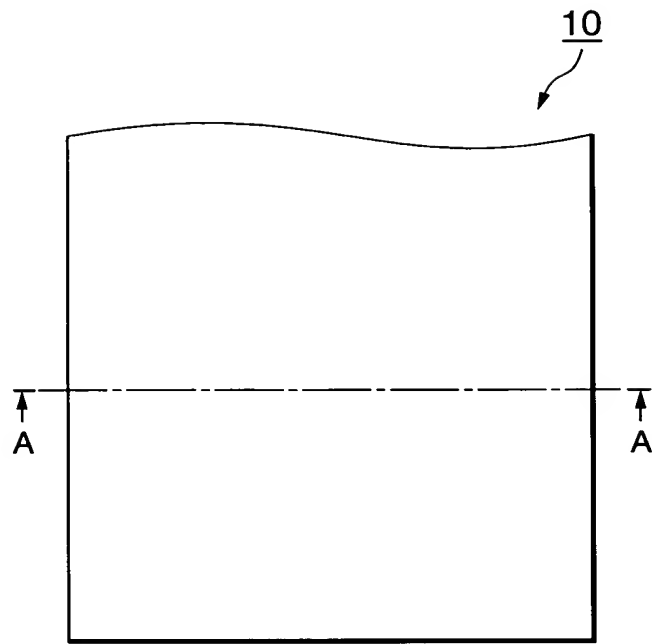
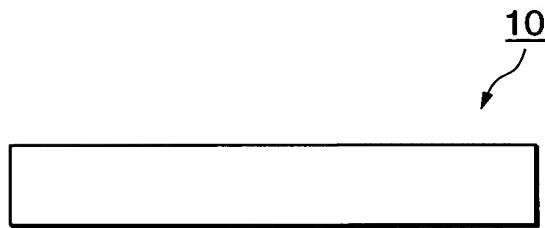


FIG.1B



MANUFACTURING PROCESS OF LEAD FRAME (FIRST STEP)

FIG.2A

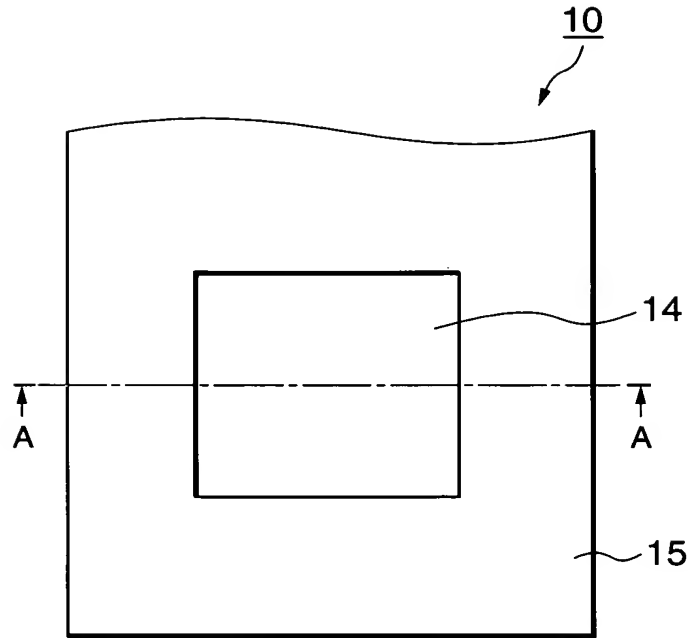
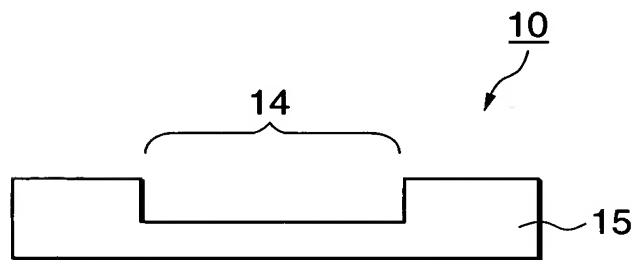


FIG.2B



MANUFACTURING PROCESS OF LEAD FRAME (SECOND STEP)

FIG.3A

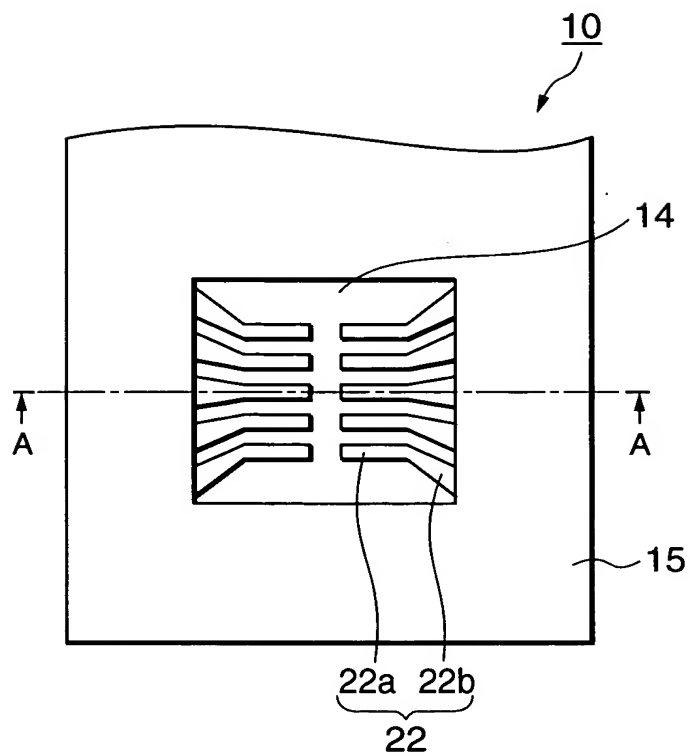
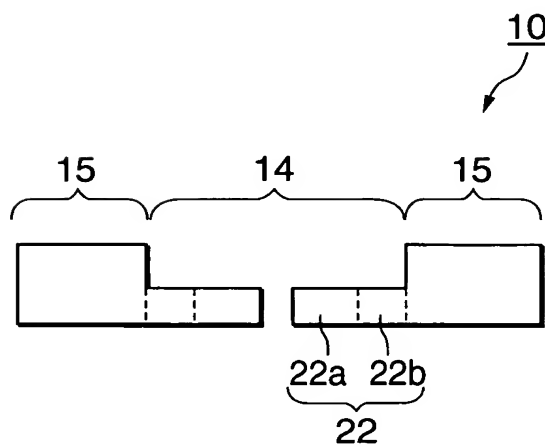


FIG.3B



MANUFACTURING PROCESS OF LEAD FRAME (THIRD STEP)

FIG.4A

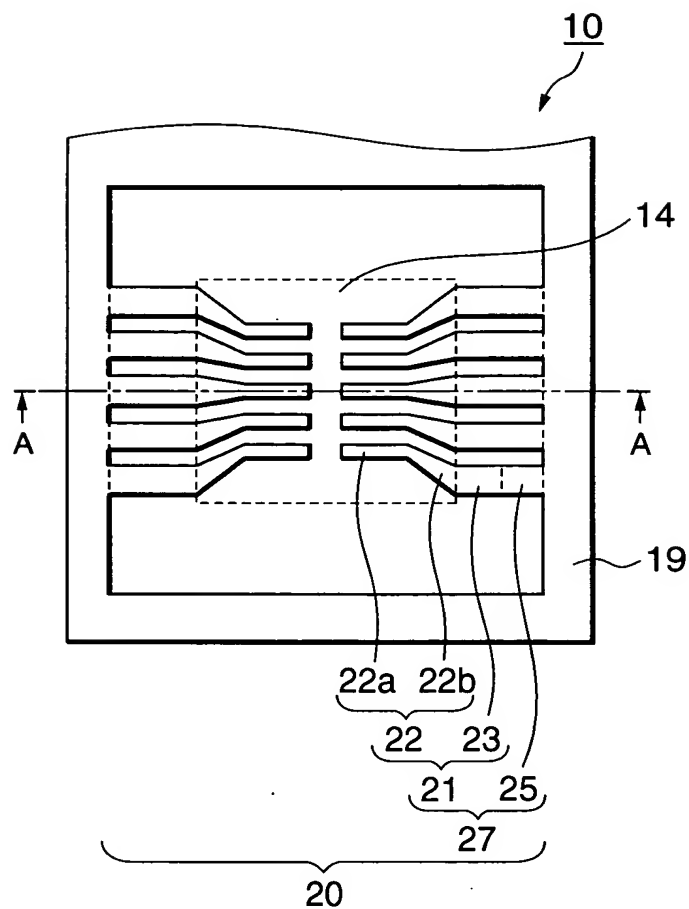
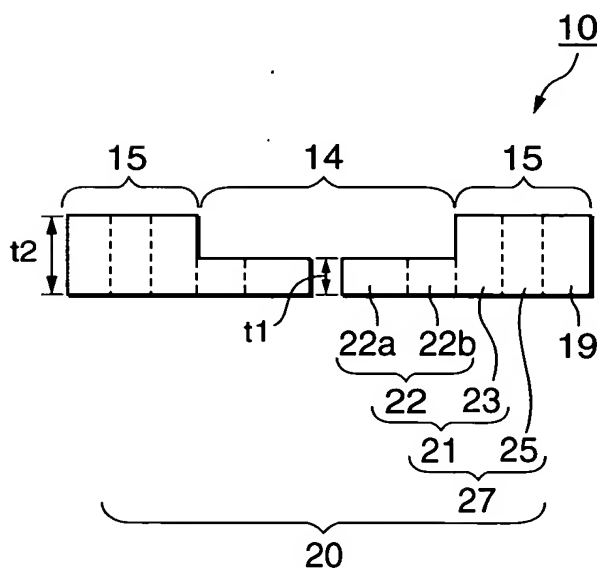


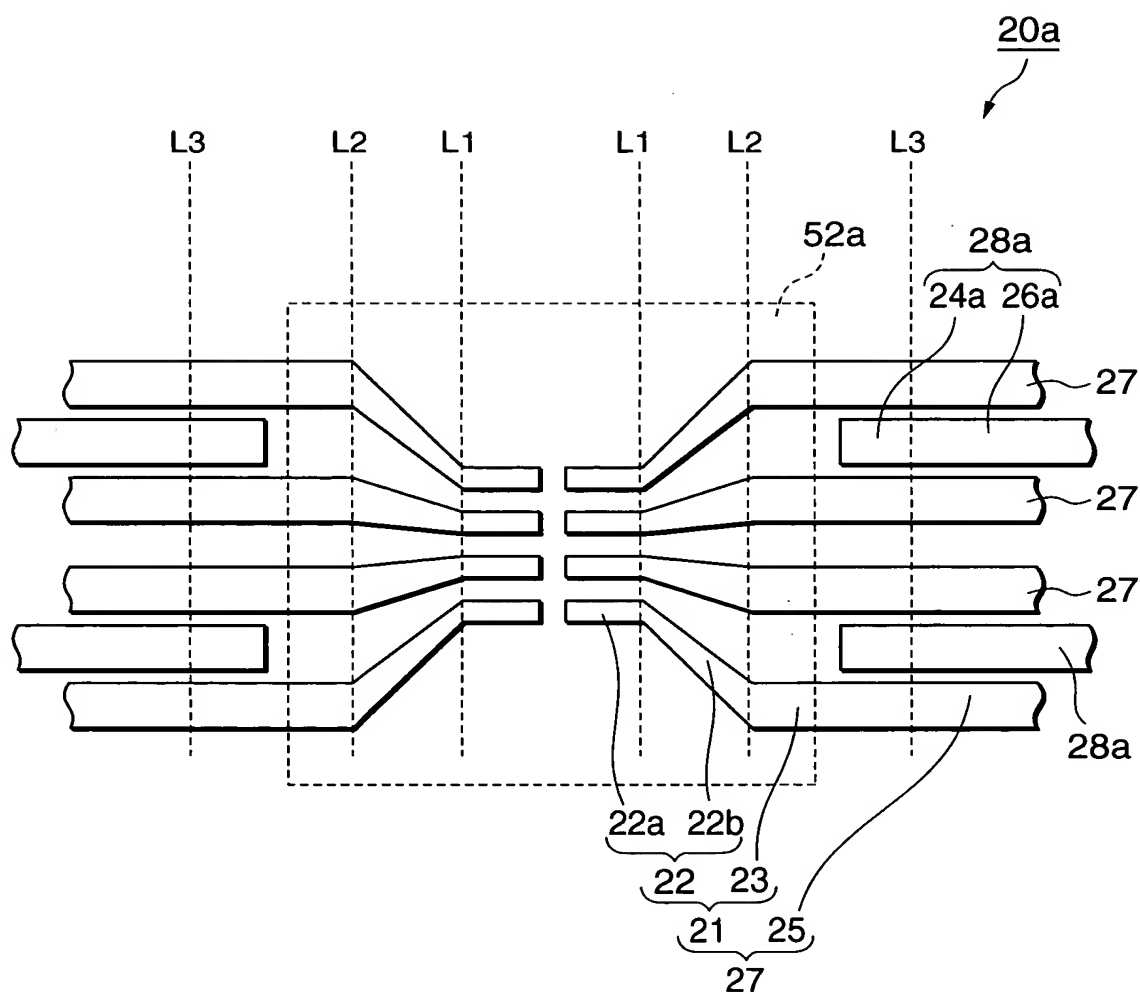
FIG.4B



MANUFACTURING PROCESS OF LEAD FRAME (FOURTH STEP)

FIRST EMBODIMENTS OF SEMICONDUCTOR DEVICE AND LEAD FRAME

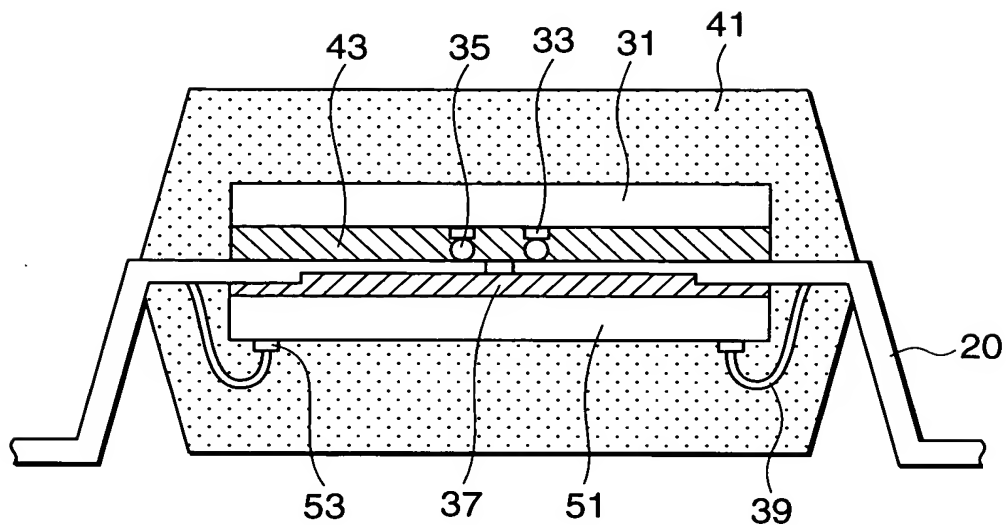
FIG.6



SECOND EMBODIMENT OF LEAD FRAME

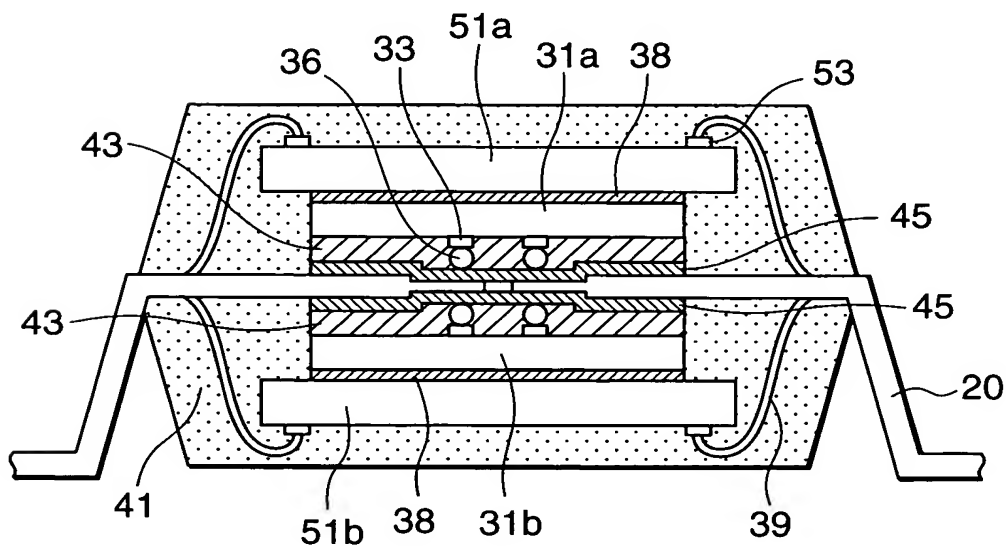
THIRD EMBODIMENT OF LEAD FRAME

FIG.8



SECOND EMBODIMENT OF SEMICONDUCTOR DEVICE

FIG.9



THIRD EMBODIMENT OF SEMICONDUCTOR DEVICE

FIG.10A

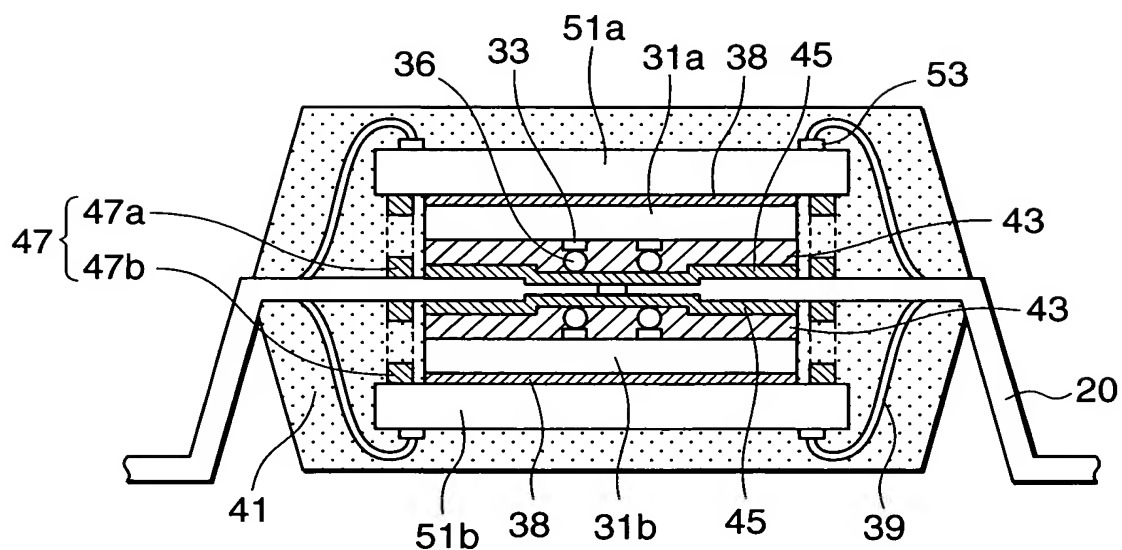
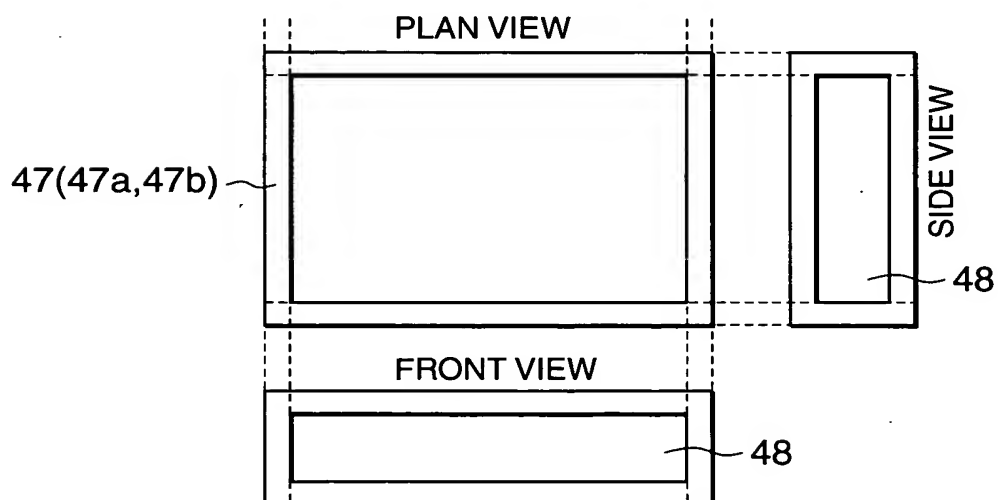
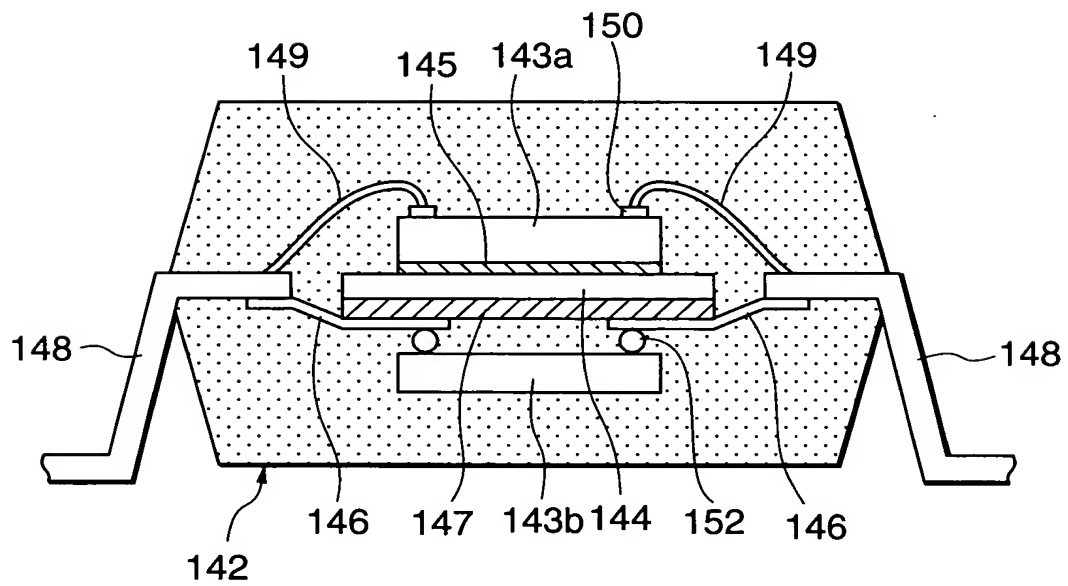


FIG.10B



FOURTH EMBODIMENT OF SEMICONDUCTOR DEVICE

FIG.11



CONVENTIONAL EXAMPLE OF SEMICONDUCTOR DEVICE